

LISTING OF THE CLAIMS

1. (Previously Presented) An imaging device, comprising:
 - a die containing an array of imaging elements; and
 - a transparent element adhesively attached to said die by an adhesive material and having a first surface facing a first surface of said die, said first surface of said transparent element having at least one adhesive flow restriction area for impeding flow of an adhesive across said first surface of said die.
2. (Canceled)
3. (Previously Presented) The imaging device of claim 1, wherein said adhesive flow restriction area comprises at least one trench.
4. (Original) The imaging device of claim 3, wherein said at least one trench has a rectangular shape.
5. (Original) The imaging device of claim 3, wherein said at least one trench has a curved shape.
6. (Original) The imaging device of claim 3, wherein said at least one trench creates a perimeter around said array of imaging elements.
7. (Original) The imaging device of claim 6, further comprising a second trench creating a perimeter around said at least one trench.
8. (Original) The imaging device of claim 3, wherein said at least one trench extends from edge to edge of said transparent element.

9. (Original) The imaging device of claim 2, wherein said adhesive flow restriction area comprises at least one protuberance.

10. (Original) The imaging device of claim 9, wherein said at least one protuberance has a curved shape.

11. (Original) The imaging device of claim 9 wherein said at least one protuberance has a rectangular shape.

12. (Original) The imaging device of claim 9, wherein said at least one protuberance has a pointed shape.

13. (Original) The imaging device of claim 9, wherein said at least one protuberance is formed of a mesa.

14. (Original) The imaging device of claim 9, wherein said at least one protuberance surrounds said array of imaging elements.

15. (Original) The imaging device of claim 14, further comprising a second protuberance surrounding said at least one protuberance.

16. (Original) The imaging device of claim 9, wherein said at least one protuberance extends from edge to edge of said transparent element.

17. (Canceled)

18. (Previously Presented) An imaging device, comprising:

a die containing an array of imaging elements; and

a transparent element adhesively attached to said die by an adhesive material and having a first surface facing a first surface of said die, said first surface of said die having at least one adhesive flow restriction area for impeding flow of an adhesive across said first surface of said die, wherein said adhesive flow restriction area comprises at least one trench.

19. (Original) The imaging device of claim 18, wherein said at least one trench has a curved shape.

20. (Original) The imaging device of claim 18, wherein said at least one trench creates a perimeter around said array of imaging elements.

21. (Original) The imaging device of claim 20, further comprising a second trench creating a perimeter around said at least one trench.

22. (Original) The imaging device of claim 18, wherein said at least one trench extends from edge to edge of said die.

23-27. (Canceled)

28. (Original) The imaging device of claim 1, wherein said transparent element is comprised of a material selected from the group consisting of glass, an optical thermoplastic material, a polyimide, a thermoset resin, a photosensitive gelatin, and a radiation curable resin.

29. (Original) The imaging device of claim 1, wherein said adhesive material at an edge of said transparent element completely covers wire bonds electrically connecting said die to conductive lines.

30. (Original) The imaging device of claim 1, wherein said die is associated with a substrate.

31. (Original) The imaging device of claim 1, wherein said die is electrically connected to conductive tape by at least one conductive structure.

32. (Original) The imaging device of claim 31, wherein said at least one conductive structure is a solder ball.

33. (Original) The imaging device of claim 1, wherein said imaging element is comprised of an array of pixels, said pixels providing electrical signals corresponding to a response from light radiation.

34. (Original) The imaging device of claim 1, wherein said imaging element is comprised of an array of pixels, said pixels capable of displaying an image corresponding to electrical signals.

35. (Original) The imaging device of claim 1, wherein a vacant space between said transparent element and said array of imaging elements is hermetically sealed by said adhesive material.

36-62. (Cancelled)

63. (Previously Presented) The imaging device of claim 18, wherein said transparent element is comprised of a material selected from the group consisting of glass, an optical thermoplastic material, a polyimide, a thermoset resin, a photosensitive gelatin, and a radiation curable resin.

64. (Previously Presented) The imaging device of claim 18, wherein said adhesive material at an edge of said transparent element completely covers wire bonds electrically connecting said die to conductive lines.

65. (Previously Presented) The imaging device of claim 18, wherein said die is associated with a substrate.

66. (Previously Presented) The imaging device of claim 18, wherein said die is electrically connected to conductive tape by at least one conductive structure.

67. (Previously Presented) The imaging device of claim 66, wherein said at least one conductive structure is a solder ball.

68. (Previously Presented) The imaging device of claim 18, wherein said imaging element is comprised of an array of pixels, said pixels providing electrical signals corresponding to a response from light radiation.

69. (Previously Presented) The imaging device of claim 18, wherein said imaging element is comprised of an array of pixels, said pixels capable of displaying an image corresponding to electrical signals.

70. (Previously Presented) The imaging device of claim 18, wherein a vacant space between said transparent element and said array of imaging elements is hermetically sealed by said adhesive material.